Express Mail Label No. EV 318163055 US

APPLICATION DATA SHEET UNDER 37 CFR §1.76

(1) Inventor Information

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Cho

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(2) Assignee Information

Name Line One::

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Address Line One::

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Address Line Two::

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City::

Yongin-city

State or Province::

Republic of Korea

Correspondence Information

Customer No.::

A- - -

3624

Name Line One::

Ruy M. Garcia-Zamor

Name Line Two::

Volpe and Koenig, P.C.

Telephone No.::

215-568-6400

Application Information (4)

Title Line One::

GOLD ALLOY BONDING WIRE FOR

Title Line Two::

SEMICONDUCTOR DEVICE

Total Drawing Sheets::

Drawing Type::

Formal

Application Type::

Utility

Docket No.::

YPL-PT015

Representative Information (5)

Representative Customer No.:: 3624

(6) Foreign Priority Information

Foreign Application One::

10-2003-0023344

Filing Date::

April 14, 2003

Country::

Korea

Priority Claimed::

YES